

C1210C331KATACTU

Aliases (C1210C331KATAC7800) SMD Comm X8G HT150C, Ceramic, 330 pF, 10%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



Click here for the 3D model.

4000

General Information	mation	
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	30 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		Specifications
Chip Size	1210	Capacitance
L	3.2mm +/-0.2mm	Measurement Condition
W	2.5mm +/-0.2mm	Tolerance
т	0.78mm +/-0.10mm	Voltage DC
S	1.5mm MIN	Dielectric Withstanding Voltage
В	0.5mm +/-0.25mm	Temperature Range
		Temp. Coefficient
Packaging Specifications		Capacitance Change with
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC

	Capacitance	330 pF
	Measurement Condition	1 MHz 1.0Vrms
	Tolerance	10%
	Voltage DC	250 VDC
	Dielectric Withstanding Voltage	625 VDC
	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

Insulation Resistance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Packaging Quantity